



Physical Interface & Carriers Japan TC Chapter

Japan Standards Winter Meetings 2023 in conjunction with SEMICON Japan 2023
Thursday, December 14, 2023
Tokyo Big Sight, Tokyo Japan/ Official Virtual TC Chapter Meeting (Hybrid)
13:00-16:00 JST

AGENDA

1.0 Welcome / Call to Order

- 1.1 Introductions
- 1.2 Meeting Reminders (*Membership Requirement, Antitrust and Intellectual Property Reminders, Effective Meeting Guidelines*)
- 1.3 Agenda Review

2.0 Review of Previous Meeting Minutes

3.0 Liaison Report

- 3.1 North America

4.0 Staff Report

5.0 Ballot Review

- 5.1 7112, Line Item Revision to SEMI E181-0423 SPECIFICATION FOR PANEL FOUP FOR PANEL LEVEL PACKAGING, SEMI E181.1-0423 - SPECIFICATION FOR PANEL FOUP FOR 510 mm – 515 mm PANEL SIZE and 12 SLOTS, SEMI E181.2-0423 - SPECIFICATION FOR PANEL FOUP FOR 510 mm – 515 mm PANEL SIZE and 6 SLOTS, SEMI E181.3-0423 - SPECIFICATION FOR PANEL FOUP FOR 600 mm – 600 mm PANEL SIZE and 12 SLOTS, SEMI E181.4-0423 - SPECIFICATION FOR PANEL FOUP FOR 600 mm – 600 mm PANEL SIZE and 6 SLOTS
- 5.2 7113, Line Item Revision to Line Item Revision to SEMI E182-0621 - SPECIFICATION FOR PANEL FOUP LOADPORT FOR PANEL LEVEL PACKAGING

6.0 Subcommittee & Task Force Reports

- 6.1 Global PIC Standards Maintenance TF
- 6.2 Japan Electron Microscopy Workflow liaison TF
- 6.3 Panel Level Packaging Panel FOUP TF
- 6.4 [Liaison: 3D Packaging & Integration JA TC Chapter] Panel Level Packaging Glass Carrier TF
- 6.5 [Liaison: 3D Packaging & Integration NA TC Chapter] Panel Level Packaging Panel TF

7.0 Old Business

- 7.1 Project Period Review
- 7.2 5-Year Review

8.0 New Business

- 8.1 SNARF Proposal for Line Item Revision to SEMI E185-1222: Specification for 300 mm Tape Frame FOUP
- 8.2 Approval request for Line Item Revision to SEMI E185-1222: Specification for 300 mm Tape Frame FOUP
- 8.3 SNARF Proposal for Line Item Revision to SEMI E184-1221E: Specification for 300 mm Tape Frame FOUP Load Port
- 8.4 Approval request for Line Item Revision to SEMI E184-1221E: Specification for 300 mm Tape Frame FOUP Load Port
- 8.5 Proposal for New TFOF: Next Gen Assembly / Test Material Handling TF



8.6 SNARF Proposal for Next Gen Assembly / Test Carrier

9.0 Action Item Review

9.1 Open Action Items

9.2 New Action Items

10.0 Next Meeting and Adjournment